

# 3.3 V 1:4 Clock Fanout Buffer

## NB3N2304NZ

### Description

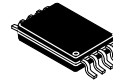
The NB3N2304NZ is a low skew 1-to 4 clock fanout buffer, designed for high speed clock distribution such as in PCI-X applications. The NB3N2304NZ guarantees low output-to-output skew. Optimal design, layout and processing minimizes skew within a device and from device-to-device.

The Output Enable (OE) pin forces the outputs LOW when LOW.

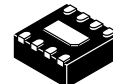
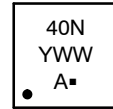
### Features

- Input/Output Clock Frequency up to 140 MHz
- Low Skew Outputs (100 ps)
- Output Enable
- Operating Range:  $V_{DD} = 3.0\text{ V to }3.6\text{ V}$
- Ideal for PCI-X and networking clocks
- Packaged in 8-pin TSSOP, 4.4 mm x 3 mm
- Industrial Temperature Range
- These are Pb-Free Devices\*

### MARKING DIAGRAM\*



TSSOP-8  
DT SUFFIX  
CASE 948S



DFN8  
MN SUFFIX  
CASE 506AA



- A = Assembly Location
- Y = Year
- WW = Work Week
- M̄ = Date Code
- = Pb-Free Package

\*For additional marking information, refer to Application Note AND8002/D.

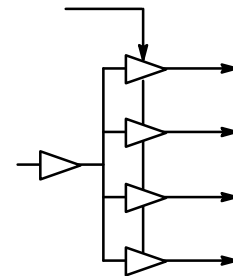


Figure 1. Simplified Logic Diagram

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NB3N2304NZ

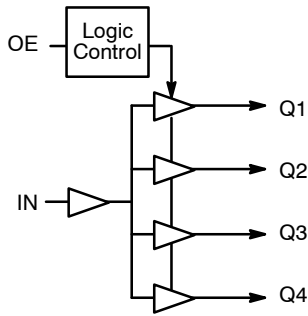


Figure 2. Block Diagram

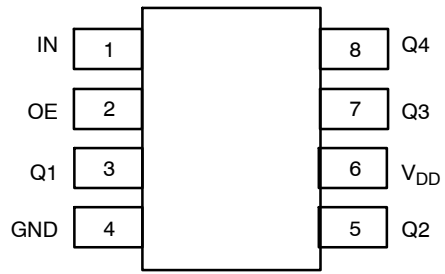


Figure 3. NB3N2304NZ Package Pinout (Top View)

Table 1. PIN DESCRIPTION

Pin #	Pin Name	Type	Description
1	IN	LVC MOS/LVTTL Input	Clock Input
2	OE	LVC MOS/LVTTL Input	Output Enable for the clock outputs. Outputs are enabled when forced HIGH. Outputs are forced to logic LOW when OE is forced LOW.
3	Q1	LVC MOS/LVTTL Output	Clock Output 1
4	GND	Power	Negative Supply Voltage; Connect to Ground, 0 V
5	Q2	(LV)CMOS/(LV)TTL Input	Clock Output 2
6	V <sub>DD</sub>	Power	Positive Supply Voltage (3.0 V to 3.6 V)
7	Q3	(LV)CMOS/(LV)TTL Output	Clock Output 3
8	Q4	(LV)CMOS/(LV)TTL Input	Clock Output 4
-	EP	Thermal Exposed Pad	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. OE, OUTPUT ENABLE FUNCTION TABLE

Inputs		Outputs
IN	OE	
L	L	L
H	L	L
L	H	L
H	H	H

# NB3N2304NZ

**Table 3. ATTRIBUTES**

Characteristics		Value
ESD Protection	Human Body Model Machine Model	> 2kV > 200 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	TSSOP-8 DFN-8	Level 3 Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-O @ 0.125 in
Transistor Count		480 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

1. For additional information, see Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>DD</sub>	Positive Power Supply	GND = 0 V		V <sub>DD</sub> + 0.5V	V
V <sub>I</sub>	Input Voltage			GND - 0.5 ≤ V <sub>I</sub> ≤ V <sub>DD</sub> + 0.5	V
T <sub>A</sub>	Operating Temperature Range, Industrial			≥ -40 to ≤ +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm 0 lfpm 500 lfpm	TSSOP-8 TSSOP-8 DFN-8 DFN-8	143 103 129 84	°C/W
T <sub>SOL</sub>	Wave Solder Pb-Free	(Note 2)		265	°C
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

# NB3N2304NZ

**Table 5. DC CHARACTERISTICS**  $V_{DD} = 3.0\text{ V to }3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C to }+85^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Unit
$I_{DD}$	Power Supply Current @ 66.66 MHz, Unloaded Outputs		12	25	mA
$V_{OH}$	Output HIGH Voltage – IOH = –24 mA – IOH = –12 mA	2.0 2.4			V
$V_{OL}$	Output LOW Voltage – IOL = 24 mA – IOL = 12 mA			0.8 0.55	V
$V_{IH}$	Input HIGH Voltage, IN and OE (Note 3)	2.0			V
$V_{IL}$	Input LOW Voltage, IN and OE (Note 3)			0.8	V
$I_{IH}$	Input HIGH Current, $V_{IN} = V_{DD}$	–50		50	$\mu\text{A}$
$I_{IL}$	Input LOW Current, $V_{IN} = 0\text{ V}$	–100		100	$\mu\text{A}$
CIN	Input Capacitance, IN, OE		5	7	pF

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

3. IN input has a threshold voltage of  $V_{DD}/2$ .

**Table 6. AC CHARACTERISTICS**  $V_{DD} = 3.0\text{ V to }3.6\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C to }+85^\circ\text{C}$  (Note 4) (Figure 4)

Symbol	Characteristic	Min	Typ	Max	Unit
$f_{in}$	Input Clock Frequency	DC		140	MHz
$t_{DCskew}$	Duty Cycle Skew = $t_2 \div t_1$ (Figure 4) Measured at 1.5 V	40	50	60	%
tr/tf	Output Rise and Fall Times; 0.8 V to 2.0 V $C_L = 25\text{ pF}$ $C_L = 10\text{ pF}$		0.9 0.6	1.5	ns
$t_{pd}$	Propagation Delay, IN-to-Qn (Note 5)	2.5	3.5	5	ns
$t_{skew}$	Output-to-Output Skew; (Note 5)			100	ps
$t_{pu}$	Powerup Time for $V_{DD}$ to Reach Minimum Specified Voltage	0.05		50	ms

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

4. All outputs loaded equally with  $C_L = 25\text{ pF}$  to GND. Duty cycle out = duty in. A  $0.01\text{ }\mu\text{F}$  decoupling capacitor should be connected between  $V_{DD}$  and GND.

5. Measured on rising edges at  $V_{DD} \div 2$ ; all outputs with equal loading.

# NB3N2304NZ

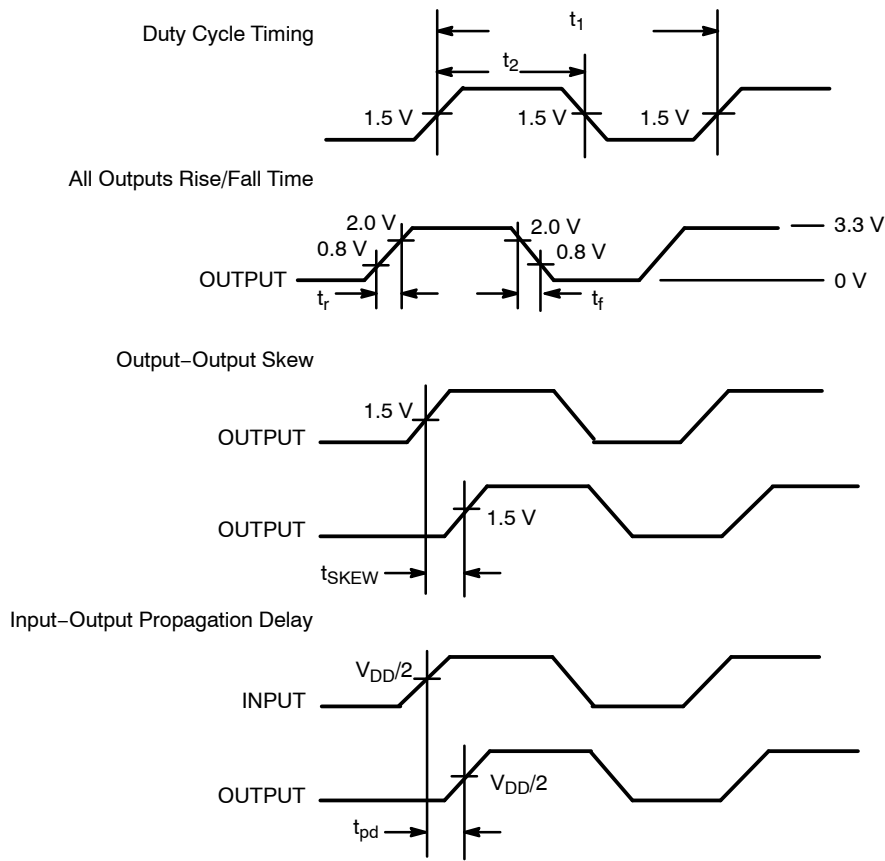


Figure 4. Switching Waveforms

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NB3N2304NZDTG	TSSOP-8 (Pb-Free)	100 Units / Rail
NB3N2304NZDTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
NB3N2304NZMNR4G*	DFN8 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*Contact a sales representative.

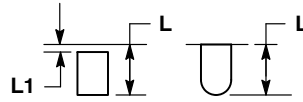
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

DFN8 2x2, 0.5P  
CASE 506AA  
ISSUE F

DATE 04 MAY 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.30 REF	
L	0.25	0.35
L1	---	0.10



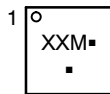
**RECOMMENDED  
SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC  
MARKING DIAGRAM\***



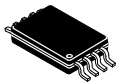
- XX = Specific Device Code
- M = Date Code
- = Pb-Free Device

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>DFN8, 2.0X2.0, 0.5MM PITCH</b>	<b>PAGE 1 OF 1</b>

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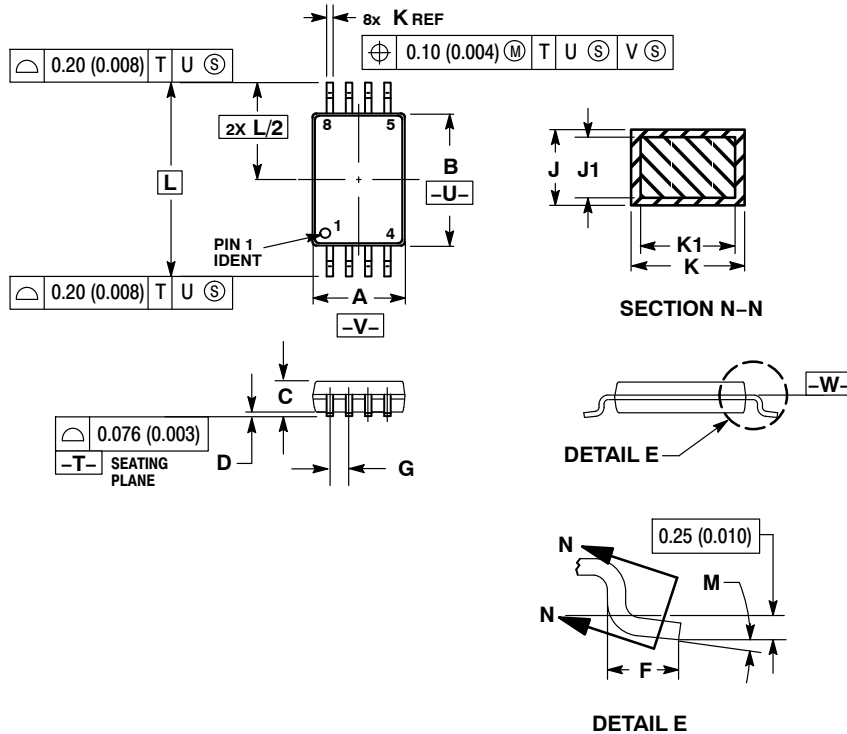
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 2:1

TSSOP-8  
CASE 948S  
ISSUE C

DATE 20 JUN 2008

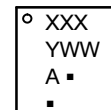


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.10	---	0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM\*



- XXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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